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AMENDMENTS TO THE CLAIMS

1-5. (Cancelled)

6. (Previously Presented) A method of manufacturing a circuit board, comprising:  
preparing a pre-preg sheet including a substrate and a resin impregnated in the substrate,  
the pre-preg sheet having a first surface and a second surface opposite to the first surface;  
placing a first metal foil on the first surface of the pre-preg sheet to provide a laminated  
body;  
compressing the laminated body at a temperature close to a softening temperature of the  
resin at a predetermined pressure;  
cooling the laminated body to have a temperature not higher than the softening  
temperature of the resin after said compressing the laminated body at the predetermined pressure;  
and  
bonding the first metal foil to the pre-preg sheet of the laminated body and hardening the  
resin.

7. (Previously Presented) The method according to claim 6, wherein said compressing  
the laminated body at the predetermined pressure comprises compressing the pre-preg sheet at a  
compression rate smaller than 10%.

8-18. (Cancelled)

19. (Currently Amended) The method according to claim 6, wherein said placing the  
first metal foil on the first surface of the pre-preg sheet to provide the laminated body further  
comprises placing a second metal foil on the second surface of the pre-preg sheet to provide the  
laminated body.

20. (Cancelled)

21. **(Currently Amended)** The method according to claim 6, further comprising:  
forming a through-hole ~~penetrating which penetrates~~ the pre-preg sheet from the first surface to the second surface of the pre-preg sheet; and  
filling the through-hole with a conductive paste.
22. **(Cancelled)**
23. **(Currently Amended)** The method according to claim 6, wherein the pre-preg sheet is in a B-stage and is compressive.
24. **(Cancelled)**
25. **(Previously Presented)** The method according to claim 6, wherein the substrate of the pre-preg sheet comprises a non-woven fabric of aromatic polyamide fiber.
26. **(Cancelled)**
27. **(Previously Presented)** The method according to claim 6, wherein the substrate of the pre-preg sheet comprises a glass fiber.
28. **(Cancelled)**
29. **(Currently Amended)** The method according to claim 6, wherein said compressing of the laminated body at a temperature close to a softening temperature of the resin comprises compressing the laminated body at a first temperature, the first temperature being close to the softening temperature of the resin, and wherein said bonding the first metal foil to the pre-preg sheet of the laminated body and hardening the resin further comprises:  
heating the laminated body at a second temperature, the second temperature being higher

than ~~[[a]] the first temperature close to the softening temperature of the resin;~~ and

heating the laminated body at a third temperature ~~higher than the second temperature~~ after said heating the laminated body at the second temperature, the third temperature being higher than the second temperature.

30. (Cancelled)

31. (Previously Presented) The method according to claim 6, wherein the resin of the pre-preg sheet has a softening range from 50°C to 130°C.

32. (New) The method according to claim 21, wherein the conductive paste includes a conductive filler and a thermosetting resin, and wherein a softening temperature of the thermosetting resin is lower than the softening temperature of the resin of the pre-preg sheet.

33. (New) The method according to claim 29, wherein the second temperature is within a flowing/hardening range of the resin.

34. (New) The method according to claim 29, wherein the third temperature is a hardening temperature of the resin.

35. (New) The method according to claim 21, wherein the resin comprises a thermosetting resin.

36. (New) The method according to claim 6, wherein said bonding the first metal foil to the pre-preg sheet of the laminated body and hardening the resin comprises:

bonding the first metal foil to the pre-preg sheet; and

hardening the resin after said cooling of the laminated body.

37. (New) The method according to claim 36, wherein said bonding of the first metal foil to the pre-preg sheet comprises bonding the first metal foil to the laminated body of the pre-preg sheet between said compressing of the laminated body and said cooling of the laminated body.